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AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of claims:

Claim 1 (previously presented): A flow sensor comprising
a housing with at least two housing sections and forming a measuring conduit between at least some of said housing sections,
a semiconductor chip comprising a sensor element arranged at a wall of the measuring conduit,
a sealing ring arranged between two of said housing sections and surrounding said semiconductor chip, said sealing ring pressing against a support formed by at least one of said housing sections, wherein said semiconductor chip is completely arranged within an area enclosed by said sealing ring, and
at least one strip conductor connected to the semiconductor chip and extending from said semiconductor chip between said support and said sealing ring and out of said housing.

Claim 2 (original): The flow sensor of claim 1 wherein said sealing ring is pressed against said strip conductor.

Claim 3 (original): The flow sensor of claim 1 wherein said strip conductor is arranged on one of said housing sections.

Claim 4 (original): The flow sensor of claim 3 further comprising a printed circuit board forming at least part of one of said housing sections, wherein said strip conductor is arranged on said printed circuit board.

Claim 5 (original): The flow sensor of claim 4 wherein the printed circuit board is arranged between the sealing ring and the support.

Claim 6 (original): The flow sensor of claim 1 further comprising a flexible support foil wherein said strip conductor is arranged on said support foil.

Claim 7 (previously presented): The flow sensor of claim 1 wherein said measuring conduit is formed by a groove in a surface of at least one of the housing sections, wherein said sealing ring surrounds said groove, said flow sensor comprising at least two connecting ducts extending through at least one of said housing sections and communicating with said measuring conduit.

Claim 8 (original): The flow sensor of claim 7 wherein said sealing ring is arranged at said surface.

Claim 9 (original): The flow sensor of claim 7 wherein said sealing ring is arranged in a

recess in said surface.

Claim 10 (original): The flow sensor of claim 1 wherein said measuring conduit is formed by a groove in a surface of a first housing section,

and wherein said semiconductor chip is arranged in a recess of a second housing section, is flush with a wall of the measuring conduit, and contacts such said first housing section.

Claim 11 (previously presented): The flow sensor of claim 10 wherein said recess has a bottom formed by a recessed surface of said second housing part and wherein the flow sensor comprises at least one spacer between said semiconductor chip and the bottom of said recess, said spacer being deformed by a force exerted by said first housing section on said semiconductor chip.

Claim 12 (original): The flow sensor of claim 11 wherein said spacer comprises a plurality of bumps located in said bottom of said recess and comprising tips, said tips being deformed by said force.

Claim 13 (original): The flow sensor of claim 12 wherein said bumps are an integral part of said second housing section.

Claim 14 (original): The flow sensor of claim 10 wherein said recess comprises a side

wall parallel to said measuring conduit, said side wall ending in recessed sections, such that said side wall ending in recessed sections, such that said side wall forms a straight top for positioning the semiconductor chip in a direction perpendicular to said measuring conduit.

Claim 15 (original): The flow sensor of claim 1 further comprising a sealant paste arranged at a crossing of said strip conductor and said sealant ring.

Claim 16 (original): The flow sensor of claim 1 wherein said semiconductor chip comprises a membrane, wherein said sensor element is arranged at least partially on said membrane, and wherein both sides of said membrane are in contact with said conduit such that a pressure drop over said membrane is substantially zero.

Claim 17 (original): The flow sensor of claim 1 wherein said semiconductor chip is arranged closer to an exit end than to an entry end of the measuring conduit.

Claim 18 (new): A flow sensor comprising
a housing with at least two housing sections forming a measuring conduit between at least some of said housing sections, wherein said measuring conduit is formed by a groove in a surface of at least one of the housing sections
at least two connecting ducts extending through at least one of said housing sections and communicating with said measuring conduit,
a semiconductor chip comprising a sensor element arranged at a wall of the measuring conduit,

a sealing ring arranged between two of said housing sections and surrounding said semiconductor chip and said groove, said sealing ring pressing against a support formed by at least one of said housing sections,

at least one strip conductor connected to the semiconductor chip and extending between said support and said sealing ring and out of said housing, and

a nose forming part of a wall of said measuring conduit and extending from one of said housing sections against said semiconductor chip, thereby dividing said semiconductor chip in a first part that is in contact with said measuring conduit and a second part that is connected to said strip conductor.

Claim 19 (new): A flow sensor comprising

a housing with at least a first and second housing section and forming a measuring conduit between said housing sections, wherein said measuring conduit is formed by a groove in a surface of at least one of the housing sections,

at least two connecting ducts extending through the second housing section and communicating with said measuring conduit, said connecting ducts ending in a surface of said second housing section, wherein said surface is opposite said measuring conduit,

a semiconductor chip comprising a sensor element arranged at a wall of the measuring conduit, and

a sealing ring arranged between said first and said second housing sections and surrounding said semiconductor chip and said groove, said sealing ring pressing against a support formed by at least one of said housing sections.

Claim 20 (new): The flow sensor of claim 19 further comprising at least one strip conductor connected to the semiconductor chip and extending between said support and said sealing ring and out of said housing.